## IN THE CLAIMS

1.(Currently Amended) An optical module mounted body comprising:
a mounting board having a mounting surface with a plurality of holes formed thereon;
an optical module placed on the mounting surface; and

a <u>self-securing</u>-member configured to secure said optical module <u>to the</u>

<u>mounting board</u>, said <u>securing</u> <u>self-securing</u> member including an upper portion, a plurality of legs extending from the upper portion and a plurality of engagement portions formed at ends of the plurality of legs,

wherein said optical module is held between said mounting board and said <u>self-securingsecuring</u> member such that the upper portion of said <u>self-securingsecuring</u> member abuts on an <u>upper opposing</u> surface of said optical module, and

wherein the plurality of legs are inserted in the plurality of holes, the plurality of engagement portion portions resiliently engaging with said mounting board to hold said optical module to said mounting board.

- 2.(Currently Amended) The optical module mounted body according to claim 1, wherein the plurality of engagement portion portions engages engage with said mounting board on an undersurface opposite said mounting surface.
- 3.(Currently Amended) The optical module mounted body according to claim 1, wherein said optical module is pressed against the mounting surface by the upper portion of said <u>self-securing</u> member.
- 4.(Currently Amended) The optical module mounted body according to claim 1, wherein the upper portion of said <u>self-securing</u> member is convex towards the upper

surface of said optical module.

5.(Currently Amended) The optical module mounted body according to claim 1, wherein said optical module comprises at least one lead pins pin for electrical connection to external circuits; and

wherein the at least one lead pins pin are is soldered to said mounting board.

6.(Currently Amended) The optical module mounted body according to claim 5, wherein said mounting board is formed with wiring holes, and wherein the at least one lead pins pin are is inserted in the wiring holes and soldered to said mounting board.

7.(Original) The optical module mounted body according to claim 1, further comprising a heat conducting member interposed between a bottom surface of said optical module and the mounting surface of said mounting board.

8.(Original) The optical module mounted body according to claim 1,
wherein said mounting board comprises at least one heat conducting member
connecting continuously the mounting surface and an undersurface opposite the mounting
surface, each end of said at least one heat conducting member being coplanar with each one
of the mounting surface and the undersurface.

9.(Currently Amended) The optical module mounted body according to claim 1, wherein said <u>self-securing-member</u> has two legs to oppose each other on both lateral sides of said optical module.

- 10.(Currently Amended) The optical module mounted body according to claim 1, wherein said <u>self-securing</u> member has two legs and one <u>another</u> leg, the two legs and the one <u>another</u> leg opposing on both longitudinal sides of said optical module.
- 11.(Currently Amended) The optical module mounted body according to claim 1, wherein said <u>self-securing</u> member has two legs on each lateral side of said optical module.
- 12.(Currently Amended) The optical module mounted body according to claim 11, wherein said optical module comprises a plurality of lead pins for electrical connection to external circuits, the plurality of lead pins protruding on both lateral sides of said optical module; and

wherein a part of the plurality of lead pins protruding on each lateral side of said optical module are received between the two legs on the <u>a</u> same side.

13. (Currently Amended) A securing method of an optical module comprising: placing said optical module on a mounting surface of a mounting board; placing a self-securing member over said optical module,

said <u>self-securing</u> member including an upper portion to that abuts abut, on an upper opposing surface of said optical module,

a plurality of legs extending from the upper portion generally alongside of said optical module,

a plurality of engagement portions being formed at ends of the plurality of legs; and

attaching said <u>self-securing</u>securing member to said mounting board, the plurality of legs being inserted in a plurality of holes formed on said mounting board and the plurality of engagement portions being <u>resiliently</u> engaged with said mounting board.

14.(Currently Amended) The method according to claim 13, wherein the upper portion of said <u>self-securing-member</u> is adapted to press the upper surface of said optical module against the mounting surface.

15.(Currently Amended) The method according to claim 13, wherein said upper portion of said <u>self-securing</u> member is convex towards said upper surface of said optical module.

16. (Original) The method according to claim 13, further comprising: inserting a lead pin of said optical module in a wiring hole formed on said mounting board; and

soldering the lead pin to said mounting board.

17. (Currently amended) An optical module mounted body comprising:

an optical module;

means for mounting said optical module; and

means for <u>resiliently and removably securing said optical module to said mounting board engaging a securing member with said mounting board, said optical module being secured therewith on said mounting board.</u>

18.(Original) The optical module mounted body according to claim 17, further

comprising means for pressing said optical module against the mounting surface.

19. (Currently Amended) A mounting board comprising:

a plate member having a mounting surface and an undersurface opposite the mounting surface; and

at least one heat conducting member embedded in said plate member and connecting continuously said mounting surface and said undersurface of said plate member;

wherein each of said at least one heat conducting member are is exposed on each one of said mounting surface and said undersurface.

20.(Currently Amended) The mounting board according to claim 19, wherein an end surface of said at least one heat conducting member is coplanar with said mounting surface.